

International IR Rectifier

勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

PD - 95014A

IRF7309PbF

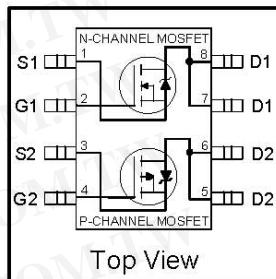
HEXFET® Power MOSFET

- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel Mosfet
- Surface Mount
- Available in Tape & Reel
- Dynamic dv/dt Rating
- Fast Switching
- Lead-Free

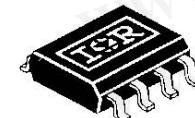
Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design for which HEXFET Power MOSFETs are well known, provides the designer with an extremely efficient device for use in a wide variety of applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics and multiple-die capability making it ideal in a variety of power applications. With these improvements, multiple devices can be used in an application with dramatically reduced board space. The package is designed for vapor phase, infra-red, or wave soldering techniques. Power dissipation of greater than 0.8W is possible in a typical PCB mount application.



	N-Ch	P-Ch
V _{DSS}	30V	-30V
R _{DS(on)}	0.050Ω	0.10Ω



SO-8

Absolute Maximum Ratings

Parameter	Max.		Units
	N-Channel	P-Channel	
I _D @ T _A = 25°C	10 Sec. Pulse Drain Current, V _{GS} @ 10V	4.7	A
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V	4.0	A
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V	3.2	A
I _{DM}	Pulsed Drain Current Ø	16	A
P _D @ T _A = 25°C	Power Dissipation (PCB Mount)**	1.4	W
	Linear Derating Factor (PCB Mount)**	0.011	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
dV/dt	Peak Diode Recovery dV/dt Ø	6.9	V/ns
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R _{θJA}	Junction-to-Amb. (PCB Mount, steady state)**	—	—	90	°C/W

** When mounted on 1" square PCB (FR-4 or G-10 Material).

For recommended footprint and soldering techniques refer to application note #AN-994.

勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787

[Http://www.100y.com.tw](http://www.100y.com.tw)

International
 I²R Rectifier

IRF7309PbF

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	N-Ch 30	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
		P-Ch -30	—	—		$V_{GS} = 0V, I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	N-Ch —	0.032	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$
		P-Ch —	0.037	—		Reference to 25°C , $I_D = -1\text{mA}$
$R_{DS(\text{ON})}$	Static Drain-to-Source On-Resistance	N-Ch —	0.050	—	Ω	$V_{GS} = 10V, I_D = 2.4\text{A}$ ③
		—	0.080	—		$V_{GS} = 4.5V, I_D = 2.0\text{A}$ ③
		P-Ch —	0.10	—		$V_{GS} = -10V, I_D = -1.8\text{A}$ ③
		—	0.16	—		$V_{GS} = -4.5V, I_D = -1.5\text{A}$ ③
$V_{GS(\text{th})}$	Gate Threshold Voltage	N-Ch 1.0	—	—	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
		P-Ch -1.0	—	—		$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
g_{fs}	Forward Transconductance	N-Ch 5.2	—	—	S	$V_{DS} = 15V, I_D = 2.4\text{A}$ ③
		P-Ch 2.5	—	—		$V_{DS} = -24V, I_D = -1.8\text{A}$ ③
I_{DSS}	Drain-to-Source Leakage Current	N-Ch —	—	1.0	μA	$V_{DS} = 24V, V_{GS} = 0V$
		P-Ch —	—	1.0		$V_{DS} = -24V, V_{GS} = 0V$
		N-Ch —	—	25		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
		P-Ch —	—	-25		$V_{DS} = -24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	N-P —	—	± 100	nA	$V_{GS} = \pm 20V$
Q_g	Total Gate Charge	N-Ch —	—	25	nC	N-Channel
		P-Ch —	—	25		$I_D = 2.6A, V_{DS} = 16V, V_{GS} = 4.5V$ ③
Q_{gs}	Gate-to-Source Charge	N-Ch —	—	2.9	nC	P-Channel
		P-Ch —	—	2.9		$I_D = -2.2A, V_{DS} = -16V, V_{GS} = -4.5V$ ③
Q_{gd}	Gate-to-Drain ("Miller") Charge	N-Ch —	—	7.9	nC	
		P-Ch —	—	9.0		
$t_{d(on)}$	Turn-On Delay Time	N-Ch 6.8	—	—	ns	N-Channel
		P-Ch 11	—	—		$V_{DD} = 10V, I_D = 2.6A, R_G = 6.0\Omega, R_D = 3.8\Omega$ ③
t_r	Rise Time	N-Ch 21	—	—	ns	
		P-Ch 17	—	—		
$t_{d(off)}$	Turn-Off Delay Time	N-Ch 22	—	—	ns	P-Channel
		P-Ch 25	—	—		$V_{DD} = -10V, I_D = -2.2A, R_G = 6.0\Omega, R_D = 4.5\Omega$ ③
t_f	Fall Time	N-Ch 7.7	—	—	ns	
		P-Ch 18	—	—		
L_D	Internal Drain Inductance	N-P —	4.0	—	nH	Between lead tip and center of die contact
L_S	Internal Source Inductance	N-P —	6.0	—		
C_{iss}	Input Capacitance	N-Ch —	520	—	pF	N-Channel
		P-Ch —	440	—		$V_{GS} = 0V, V_{DS} = 15V, f = 1.0\text{MHz}$ ③
C_{oss}	Output Capacitance	N-Ch —	180	—	pF	P-Channel
		P-Ch —	200	—		$V_{GS} = 0V, V_{DS} = -15V, f = 1.0\text{MHz}$ ③
C_{rss}	Reverse Transfer Capacitance	N-Ch —	72	—	pF	
		P-Ch —	93	—		

Source-Drain Ratings and Characteristics

Parameter		Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	N-Ch —	—	1.8	A	
		P-Ch —	—	-1.8		
I_{SM}	Pulsed Source Current (Body Diode) ①	N-Ch —	—	16		
		P-Ch —	—	-12		
V_{SD}	Diode Forward Voltage	N-Ch —	—	1.0	V	$T_J = 25^\circ\text{C}, I_S = 1.8A, V_{GS} = 0V$ ③
		P-Ch —	—	-1.0		$T_J = 25^\circ\text{C}, I_S = -1.8A, V_{GS} = 0V$ ③
t_{rr}	Reverse Recovery Time	N-Ch 47	71	—	ns	N-Channel
		P-Ch 53	80	—		$T_J = 25^\circ\text{C}, I_F = 2.6A, dI/dt = 100\text{A}/\mu\text{s}$ ③
Q_{rr}	Reverse Recovery Charge	N-Ch 56	84	—	nC	P-Channel
		P-Ch 66	99	—		$T_J = 25^\circ\text{C}, I_F = -2.2A, dI/dt = 100\text{A}/\mu\text{s}$ ③
t_{on}	Forward Turn-On Time	N-P —	Intrinsic turn-on time is negligible (turn-on is dominated by $I_S + L_D$)			

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 23)

② N-Channel $I_{SD} \leq 2.4A$, $dI/dt \leq 73\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$
 P-Channel $I_{SD} \leq -1.8A$, $dI/dt \leq 90\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$

③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

IRF7309PbF

N-Channel

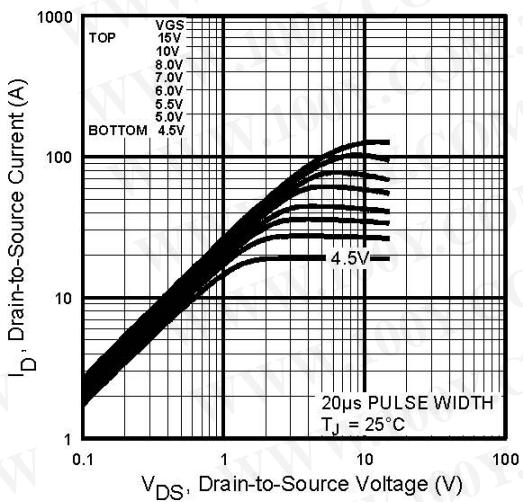


Fig 1. Typical Output Characteristics,
 $T_J = 25^\circ\text{C}$

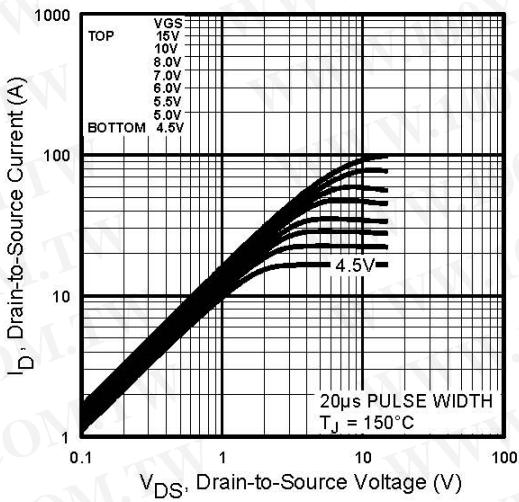


Fig 2. Typical Output Characteristics,
 $T_J = 150^\circ\text{C}$

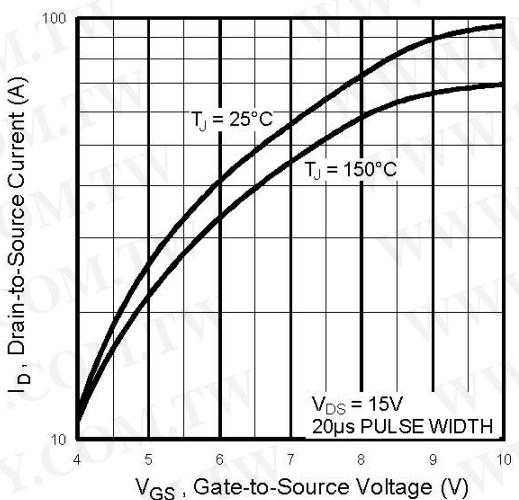


Fig 3. Typical Transfer Characteristics

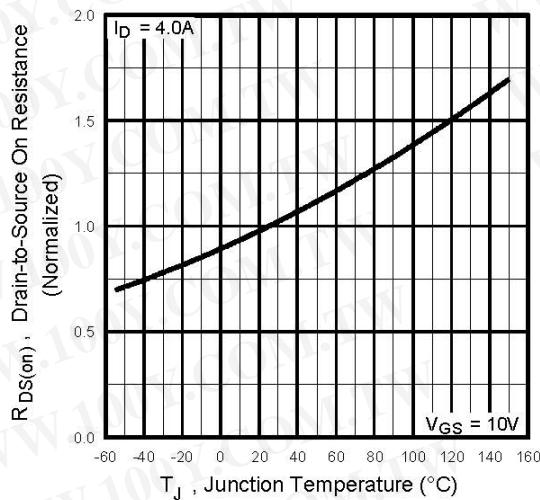


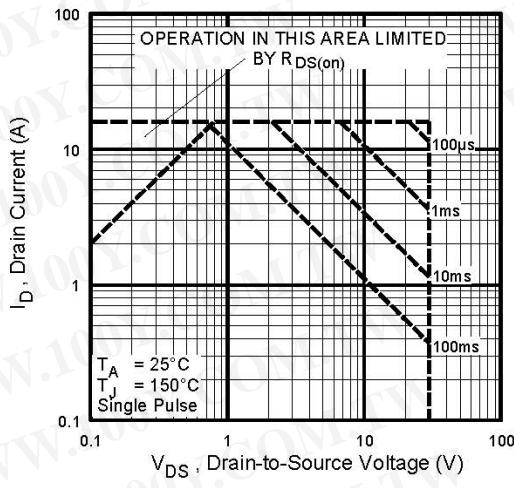
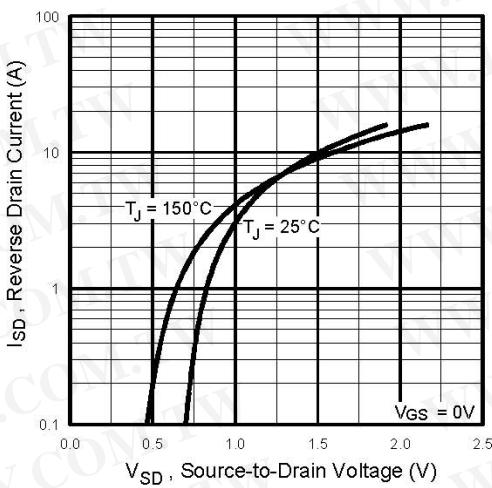
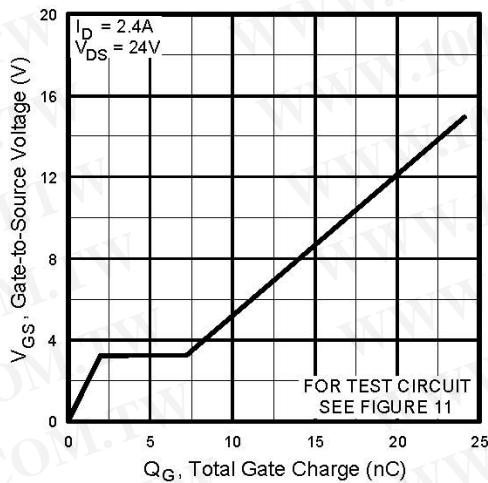
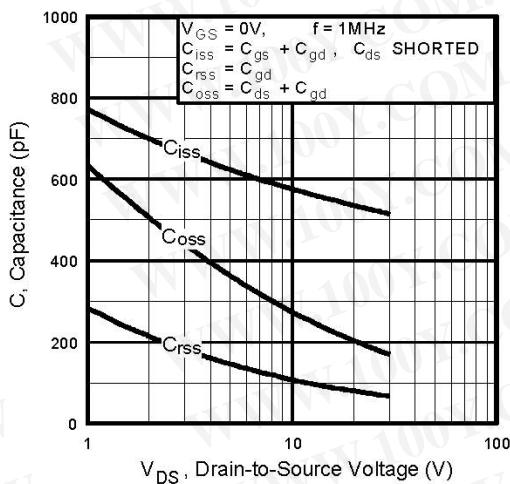
Fig 4. Normalized On-Resistance
 Vs. Temperature

勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

International
 Rectifier

IRF7309PbF

N-Channel



International
IR Rectifier

勝特力材料 886-3-5753170
胜特力电子(上海) 86-21-34970699
胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

IRF7309PbF

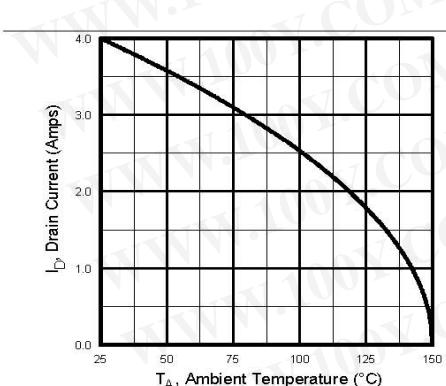


Fig 9. Max. Drain Current Vs. Ambient Temp.

N-Channel

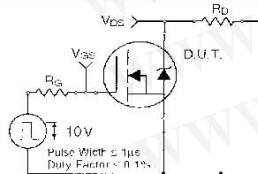


Fig 10a. Switching Time Test Circuit

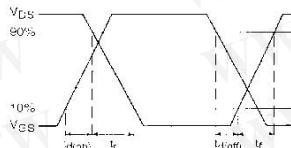


Fig 10b. Switching Time Waveforms

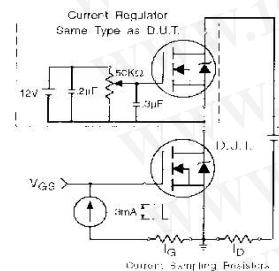


Fig 11a. Gate Charge Test Circuit

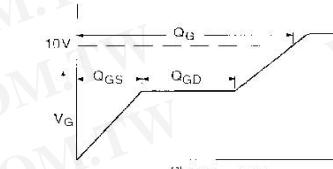


Fig 11b. Basic Gate Charge Waveform

P-Channel

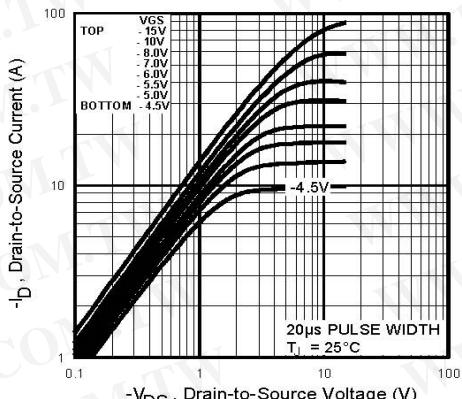


Fig 12. Typical Output Characteristics, $T_J = 25^\circ\text{C}$

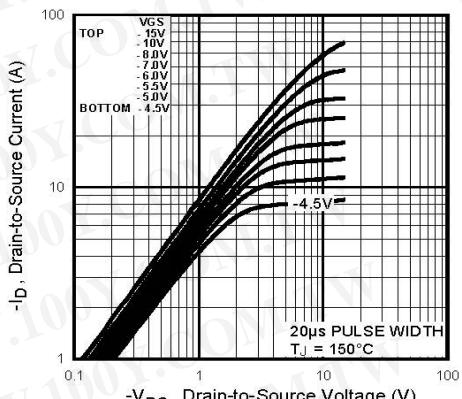


Fig 13. Typical Output Characteristics, $T_J = 150^\circ\text{C}$

勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

IRF7309PbF

International
 Rectifier

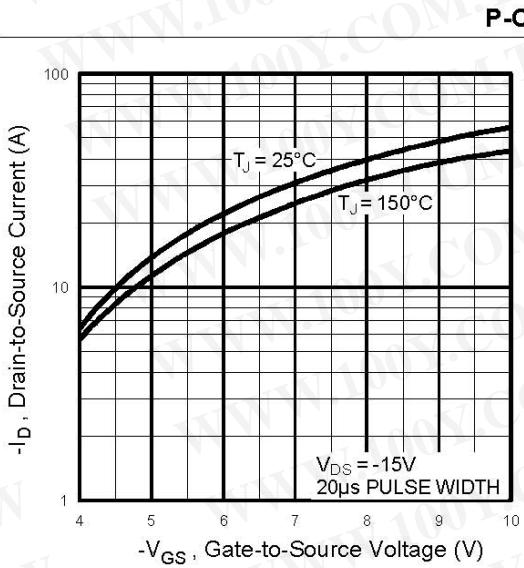


Fig 14. Typical Transfer Characteristics

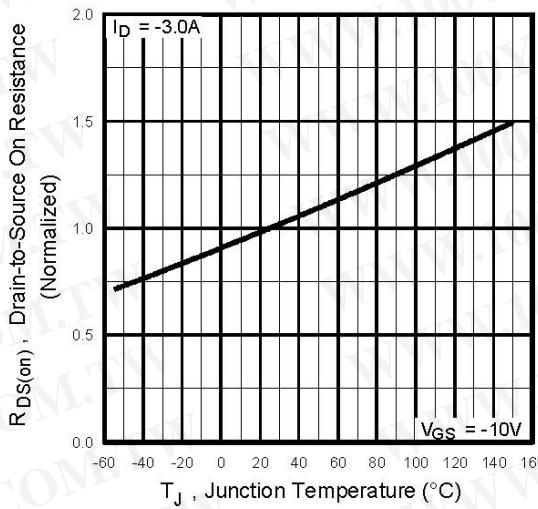


Fig 15. Normalized On-Resistance Vs. Temperature

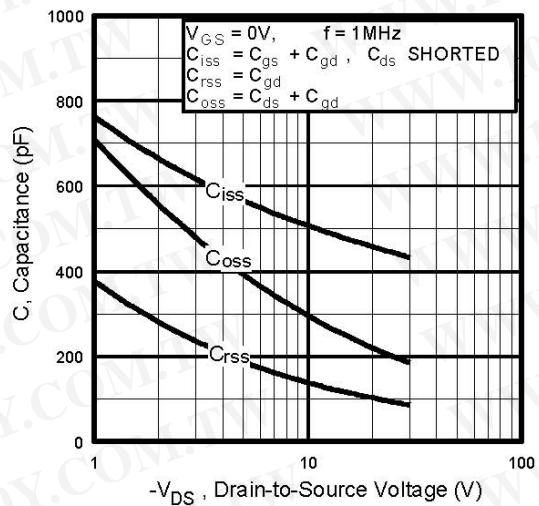


Fig 16. Typical Capacitance Vs. Drain-to-Source Voltage

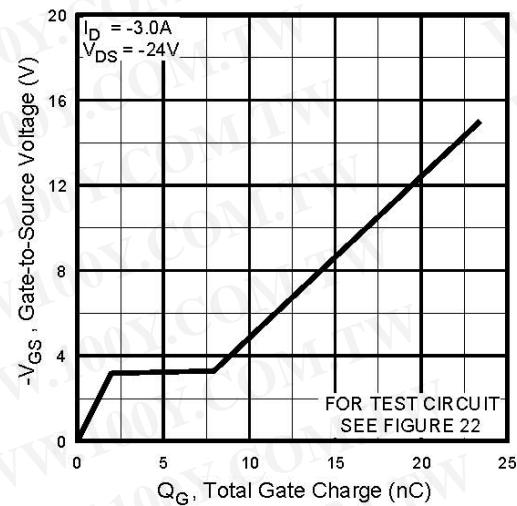
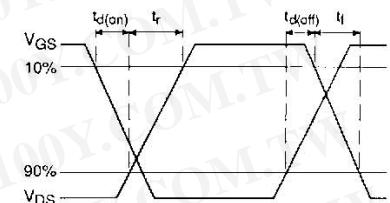
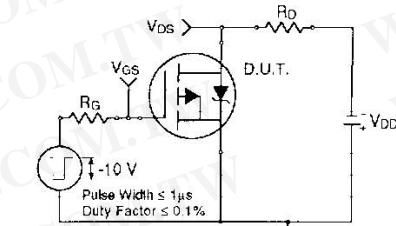
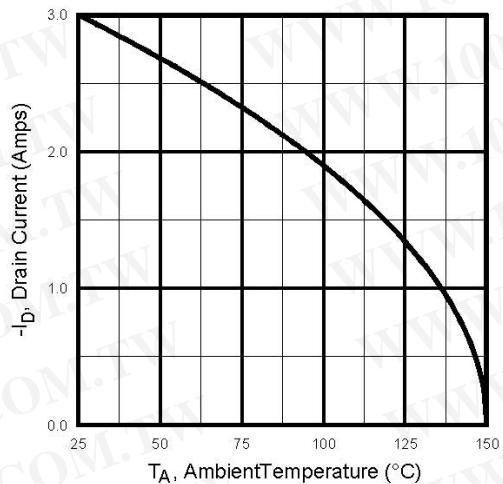
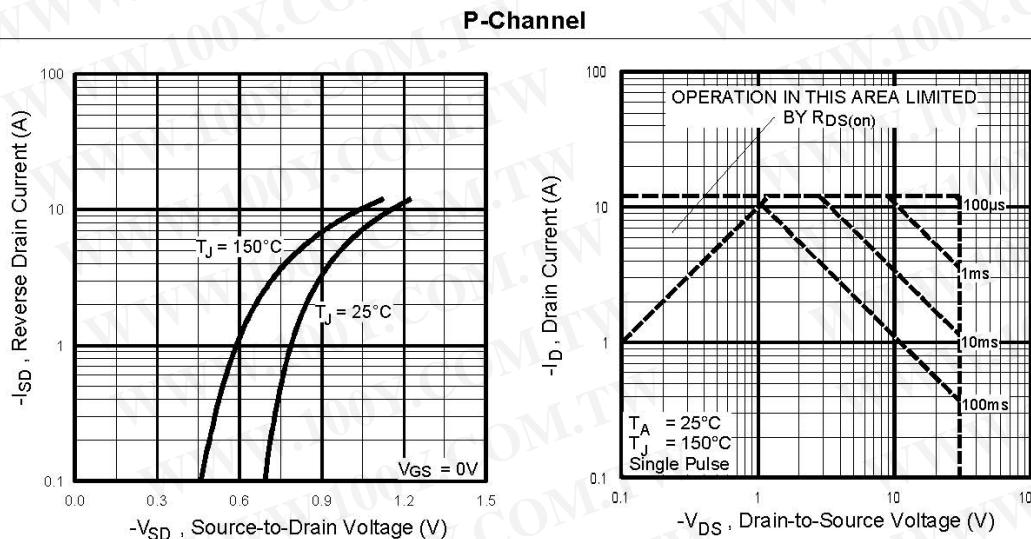


Fig 17. Typical Gate Charge Vs. Gate-to-Source Voltage

International
IR Rectifier

勝特力材料 886-3-5753170
胜特力电子(上海) 86-21-34970699
胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

IRF7309PbF



勝特力材料 886-3-5753170
 勝特力電子(上海) 86-21-34970699
 勝特力電子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

IRF7309PbF

International
 Rectifier

P-Channel

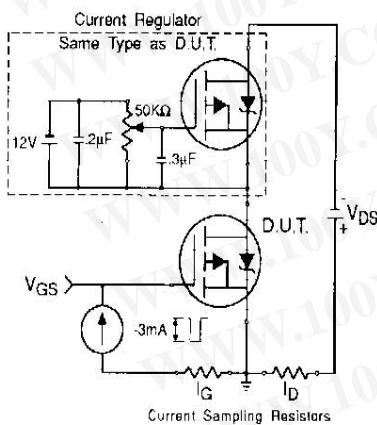


Fig 22b. Gate Charge Test Circuit

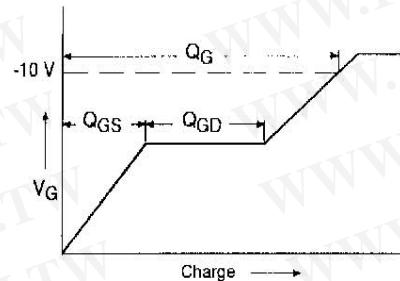


Fig 22b. Basic Gate Charge Waveform

N- and P-Channel

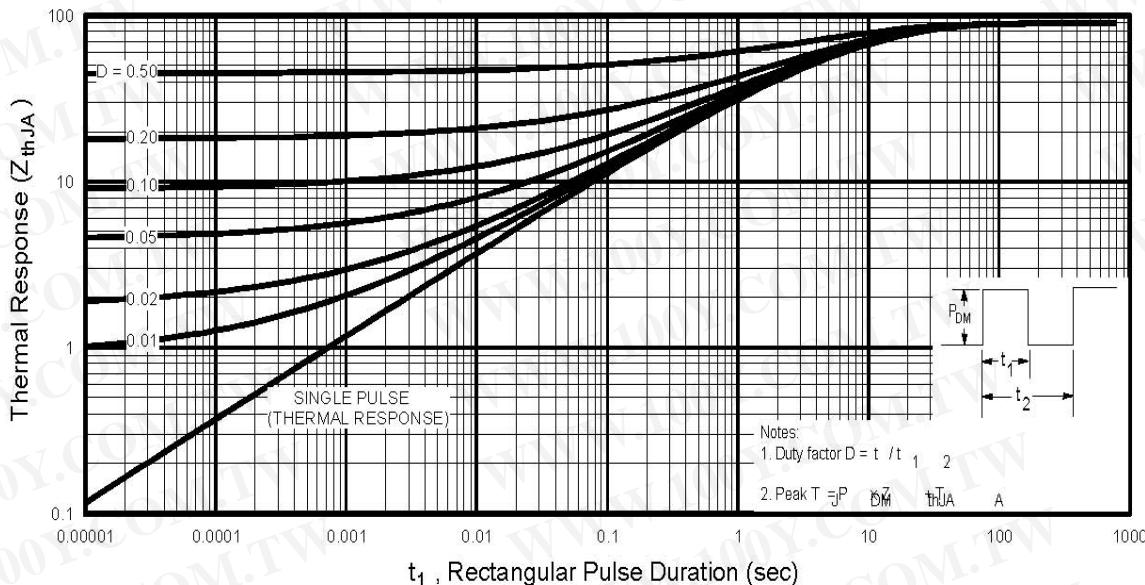


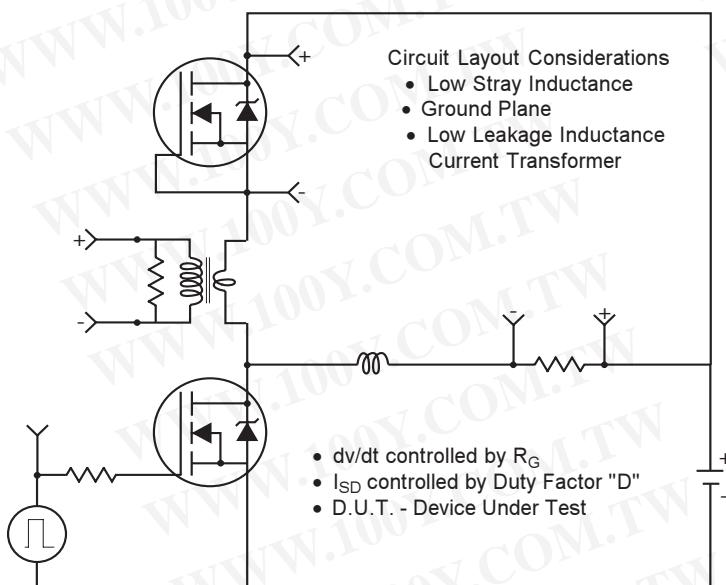
Fig 23. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

International
IR Rectifier

勝特力材料 886-3-5753170
勝特力电子(上海) 86-21-34970699
勝特力电子(深圳) 86-755-83298787
Http://www.100y.com.tw

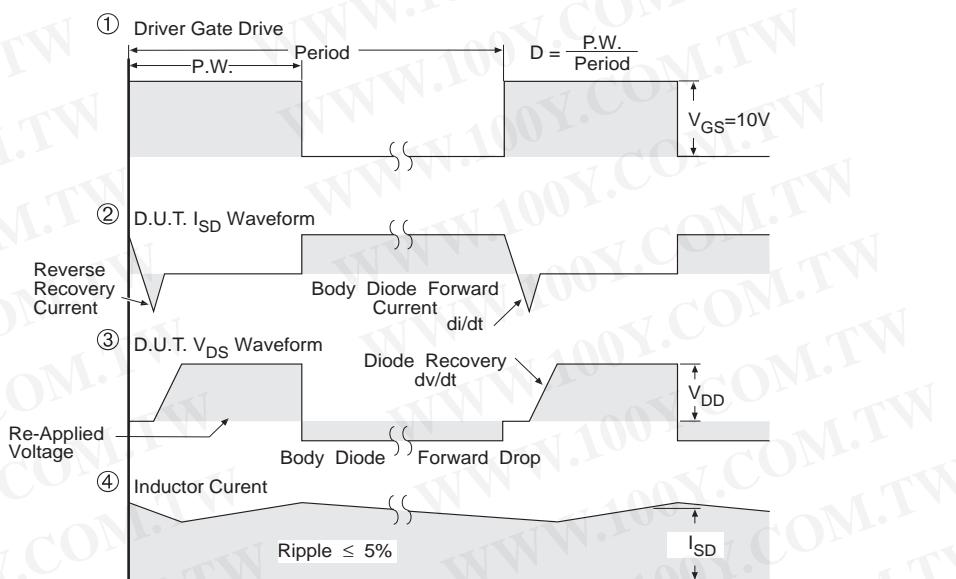
IRF7309PbF

Peak Diode Recovery dv/dt Test Circuit



* Reverse Polarity for P-Channel

** Use P-Channel Driver for P-Channel Measurements



*** $V_{GS} = 5.0V$ for Logic Level and 3V Drive Devices

Fig 24. For N and P Channel HEXFETs

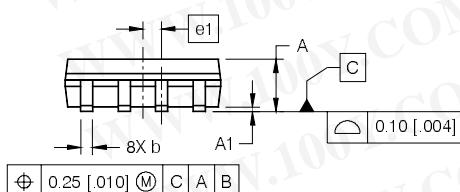
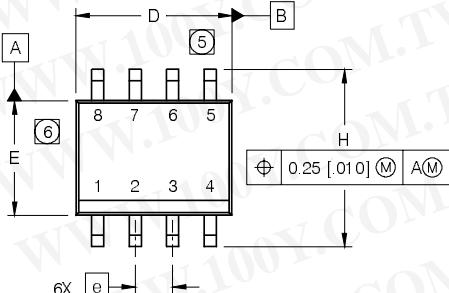
勝特力材料 886-3-5753170
 胜特力电子(上海) 86-21-34970699
 胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

International
 Rectifier

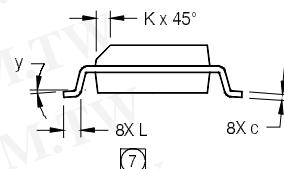
IRF7309PbF

SO-8 Package Details

Dimensions are shown in millimeters (inches)

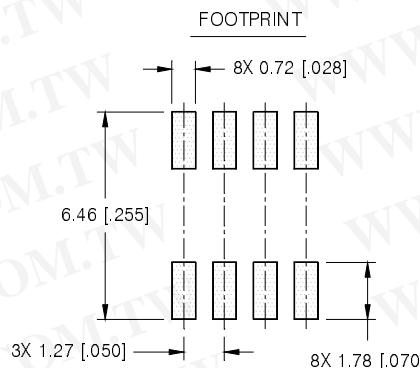


DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050	BASIC	1.27	BASIC
e 1	.025	BASIC	0.635	BASIC
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



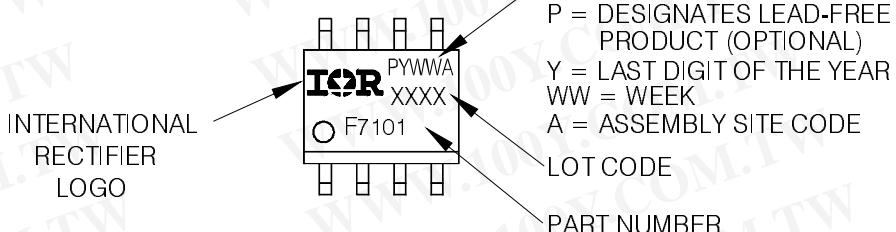
NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)

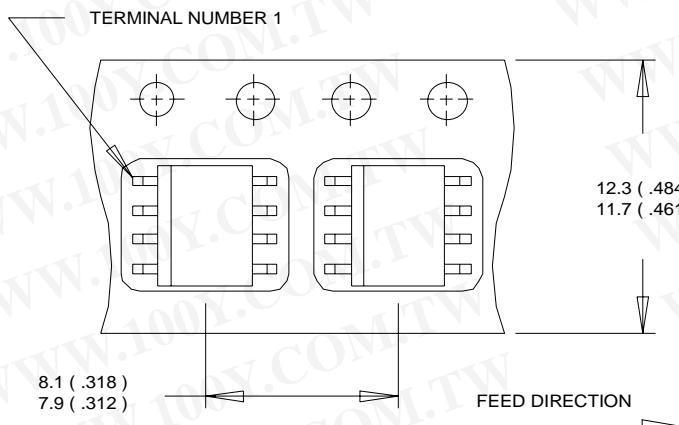


International
IR Rectifier

勝特力材料 886-3-5753170
胜特力电子(上海) 86-21-34970699
胜特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

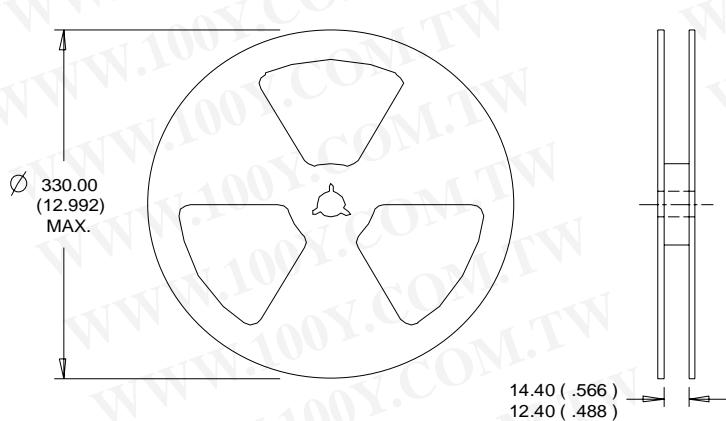
IRF7309PbF

SO-8 Tape and Reel



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.

International
IR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information.04/2007